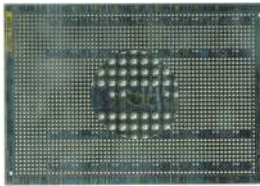
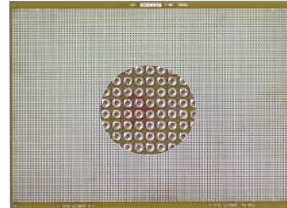


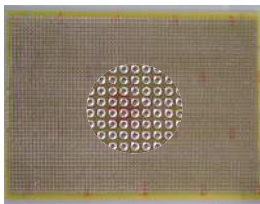
## Round Pads-Per-Hole with 0.042" Holes, .100" Grid



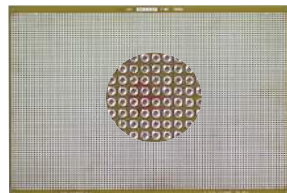
**8008 4.5"Hx6.5"L x .062" TH**  
 0.100" grid, UNIQUE circuit pattern features full voltage and ground planes on both sides with isolated plated-thru holes. 0.080" solder pads and Surface Mount cap positions for discreet decoupling capacitors. Solder coated pattern.  
 Material: FR4  
 WW Terminals: T44, T46, T49, T68  
 Solder Terminals: T42-1  
 WW Socket Pin: R32



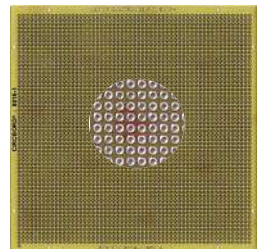
**8012 9.2"Hx11.0"L x .062" TH**  
 0.100" grid Pad-Per-Hole Pattern. .042" holes plated thru with .080" isolated solder pad around each hole on both sides.  
 16-Pin DIP= 72.  
 Material: FR4.  
 WW Terminals: T44, T46, T49, T68.  
 Solder Terminals: T42-1, K24C  
 WW Socket Pin: R32



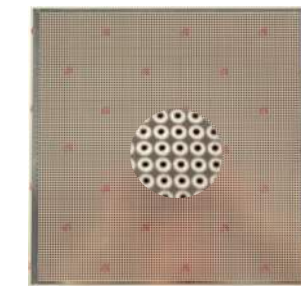
**8006 5.0"Hx13.25"L x .062" TH**  
 0.100" grid Pad-Per-Hole Pattern copper plated-thru holes both sides .042" holes with .080" isolated solder pad around each hole on both sides  
 16-Pin DIP= 154  
 Material: FR4 Epoxy Glass  
 WW Terminals: T44, T46, T49, T68  
 Solder Terminals: T42-1  
 WW Socket Pin: R32



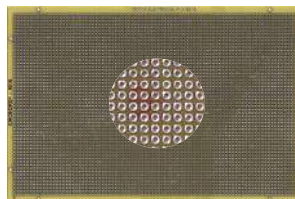
**8013 10.5"Hx18.0"L x .062" TH**  
 0.100" grid Pad-Per-Hole Pattern on both sides. Isolated 0.080" pads with 0.042" holes plated-thru copper. Unrestricted component placement.  
 Solder coated pattern  
 16-Pin DIP= 175  
 Material: FR4.  
 WW Terminals: T44, T46, T49, T68.  
 Solder Terminals: T42-1  
 WW Socket Pin: R32



**8016-1 6.0"H x 6.0"L x .062" TH**  
 0.100" grid Pad-Per-Hole Pattern on one side only, 0.042" holes  
 Small economical size.  
 Solder coated pattern  
 Material: FR4  
 WW Terminals: T44, T46, T49, T68  
 Solder Terminals: T42-1  
 WW Socket Pin: R32



**106P106-1 10.6"Hx10.6"L .062" TH**  
 0.100" grid Pad-Per-Hole & peripheral Ground Plane on both sides .042" holes not plated thru with .080" isolated solder pad around each hole  
 16-Pin DIP= 275  
 Material: CEM-1  
 WW Terminals: T44, T46, T49, T68  
 Solder Terminals: T42-1  
 WW Socket Pin: R32



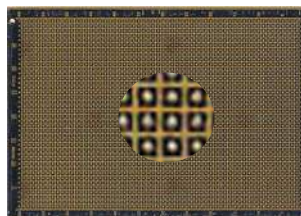
**8016 6.0"H x 9.0"L x .062" TH**  
 0.100" grid Pad-Per-Hole Pattern on both sides, 0.042" holes plated-thru copper. Unrestricted component placement.  
 Solder coated pattern  
 16-Pin DIP capacity = 165  
 Material: FR4  
 WW Terminals: T44, T46, T49, T68  
 Solder Terminals: T42-1  
 WW Socket Pin: R32



**106P180-4 10.5"Hx18.0"Lx.062" TH**  
 0.100" grid Pad-Per-Hole Pattern on both sides. Etched ground plane surrounds 0.080" pads on both sides. 0.042" holes plated-thru copper. Unrestricted component placement.  
 Solder coated pattern.  
 16-Pin DIP = 175  
 Material: FR-4  
 WW Terminals: T44, T46, T49, T68  
 Solder Terminals: T42-1  
 WW Socket Pin: R32



**106P70-4 7.0"H x 10.6"L x .062" TH**  
 0.100" grid Pad-Per-Hole Pattern on both sides. Etched ground plane surrounds 0.080" pads on both sides. 0.042" holes plated-thru copper. Solder coated pattern.  
 16-Pin DIP= 175  
 Material: FR4  
 WW Terminals: T44, T46, T49, T68  
 Solder Terminals: T42-1  
 WW Socket Pin: R32



**8003 4.50"Hx6.50"L x .062" TH**  
 0.100" grid Pad-Per-Hole Pattern & peripheral Ground Plane on one side only  
 Single-sided with no etch & plating on reverse side .042" holes not plated thru  
 .085" square isolated solder pad  
 16-Pin DIP= 60  
 Material: CEM-1  
 WW Terminals: T44, T46, T49, T68  
 Solder Terminals: T42-1  
 WW Socket Pin: R32

Circbord